

研磨装置の販売提携を開始しました

OSTECH

Mission/企业使命:



Develop and introduce new & advanced lapping/polishing products and technologies to China Customers;
专注于研磨、抛光先进技术的研发及提供;

A total solution supplier in the application of Lapping / Polishing & Fine Grinding;
在研磨、抛光和精密磨削应用上全面解决方案的提供;

致领—创造精密平面加工的先进技术

Innovative technologies in precise flat surface processing

科技型中小企业，专注于精密平面加工领域整体解决方案的提供
SME of Science & Technology, engages in total solution providing in precise flat surface processing



有进出口资质，业务类型含括生产制造和贸易
Has importing & exporting license, business type including manufacturing and trading.

●注册资金：4750万元；Registered capital: RMB 47.5M

●工厂面积：9500m²；Facility area: 9500m²



致领一创造精密平面加工的先进技术

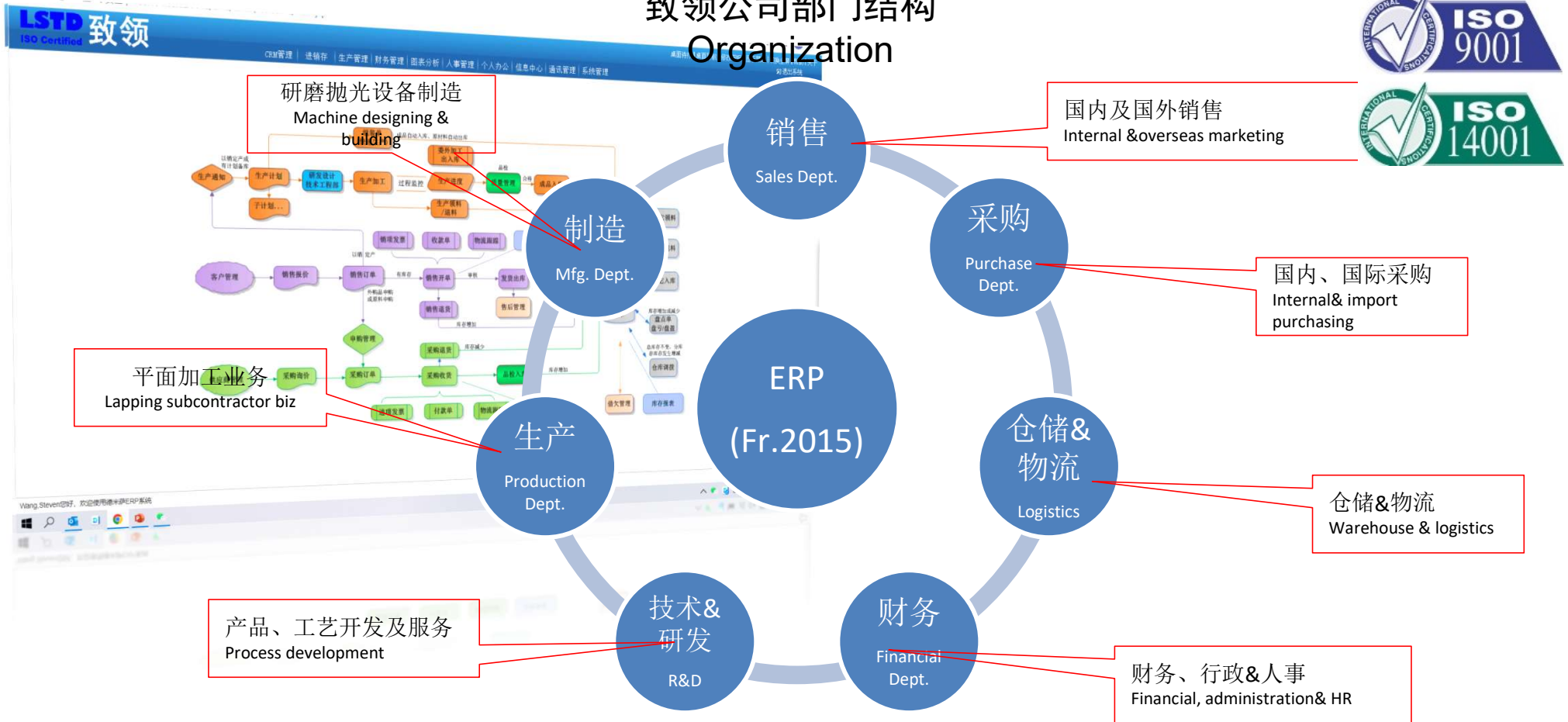
Innovative technologies in precise flat surface processing

Milestone

2011	• 公司注册成立，办公室位于上海市外高桥保税区，工厂位于浦东川沙;/Company registered in Shanghai • 办公面积300m2,工厂面积500m2 / Office area 300m2, factory area 500m2	
2015	• 公司通过ISO 9001质量体系认证/ISO 9001 registered • 厂房面积扩增300m2	
2016	• 公司整体搬迁至上海市长兴岛/Company moves to Changxing Island, Shanghai • 公司办公及厂房总面积1500m2 / Facility area 1500m2	
2017	• 工厂扩增至2300m2 / Facility expanded to 2300m2	
2019	• 公司通过ISO 14001环境体系认证/ISO 14001 registered • 公司厂房扩增至3500m2/Facility expanded to 3500m2	
2019	• 被评定为国家高新技术企业/Certified as state high tech company	
2020	• 厂房扩增至4900m2/Facility expanded to 4900m2	
2021	• 子公司上海致领研磨科技有限公司评为国家高新技术企业/Son company Shanghai Lapping Tech Co.,Ltd certified as state high tech company	
2022	• 迁入新址，厂房及办公总面积扩增至6500m2/Move to new facility, total area 6500m2	
2023	• 厂房面积扩增至8200m2，完成 Pre-A轮融资 (中芯聚源,金浦智能)/Total facility expanded to 8200m2, Pre-A financing	
2024	• 启动半导体研发中心建设，首条碳化硅自动化抛光线交付/Start up construction of semiconductor R&D center, deliver first SiC wafer automatic polishing line	
2025	• 总面积扩建至10000m2,设立日本代表处/Facility expanded to 10000m2,Setup Japan rep-office	

致领—创造精密平面加工的先进技术
Innovative technologies in precise flat surface processing

致领公司部门结构 Organization



致领—创造精密平面加工的先进技术

Innovative technologies in precise flat surface processing

Location/公司地址: 上海市长兴岛长涛路377号
377 Changtao Road, Changxing Island, Shanghai China





进口&出口
Import & Export

晶片工艺开发及加工服务
Wafer process R&D & subcontract service



工艺开发
Process R&D



设计
&
制造
Design &
Manufacturing



生产加工
Production



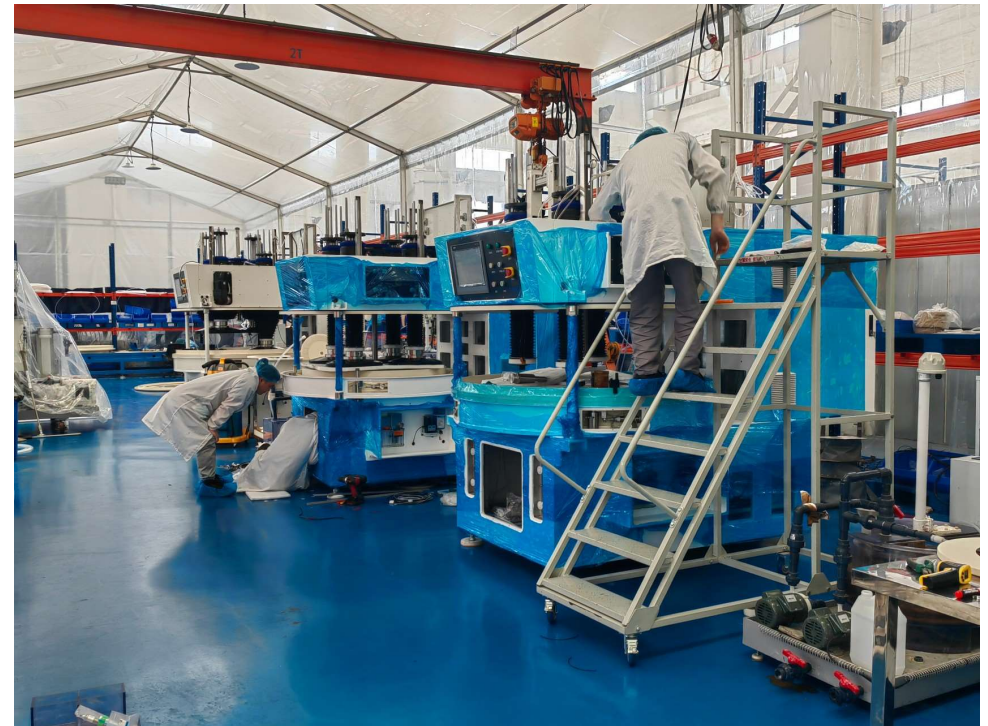
加工及装配区(常规设备)

Machining& Assembling Area (for normal Machines)



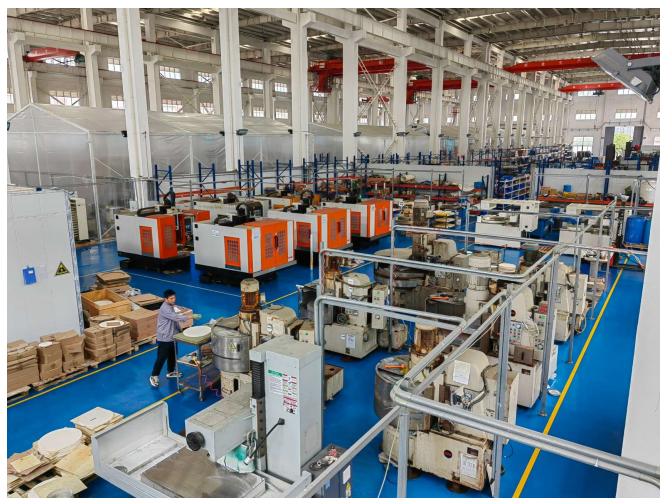
洁净装配区(半导体设备)

Clean Assembling Area (for Semiconductor Machines)



生产区

Production Area (job shop)



Ceramics /metal
parts



Semiconductor parts



Wafers

仓储及物流区

Warehouse and Logistics Area



工艺研发 Process R&D

半导体工艺研发区 Semiconductor process R&D area



工业应用工艺研发区 Industrial application R&D area



半导体零部件生产及工艺研发区 Semiconductor parts production and R&D area



办公区 Office

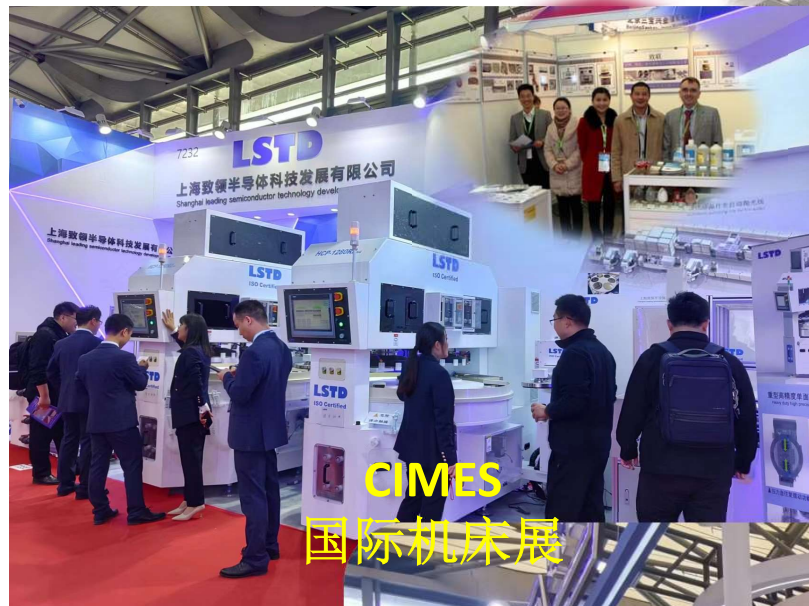


Main Office
主办公室



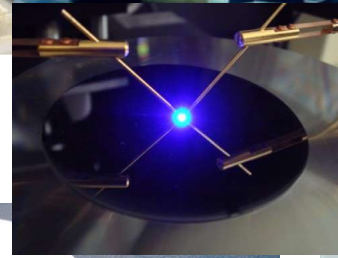
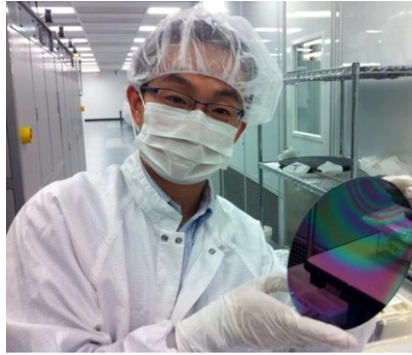
Designing Department
设计部门

Exhibition/公司展会:



Industry/服务行业:

- Semiconductor 半导体
- Opto-Electronics 光电子
- Precision Optics 精密光学
- Precision Ceramics 精密陶瓷
- Aeronautics & Astronautics 航空航天
- Nuclear Plant 核能发电
- Petroleum Exploitation 石油开采
- Industrial Application 工业应用



Products & Service/产品及服务:



Machine
设备

Consumable
耗材

Parts & Tools
配件&工具

Machine Modi &
Repair
设备维修&改造服务

制程服务
Process
Developing

Subcontractors
研磨/抛光代工服务

Lapping – Polishing – Fine Grinding

A total solution provider
完整解决方案

Products & Service/产品及服务:



Machine/设备

Machine
设备&系统

Consumable
耗材

Parts & Tools
配件&工具

Machine Modi &
Repair
设备维修&改造服务

制程服务
Process
Developing

Subcontractors
研磨/抛光代工服务



Lapping / Polishing Machines , Production Lines & Systems

Products & Service/产品及服务:



Consumable/耗材

Machine
设备

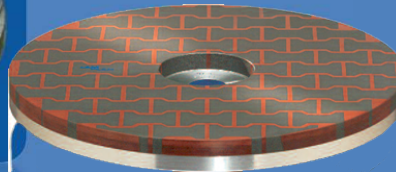
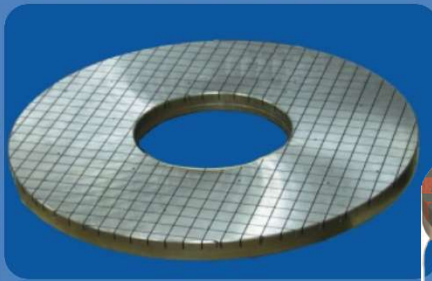
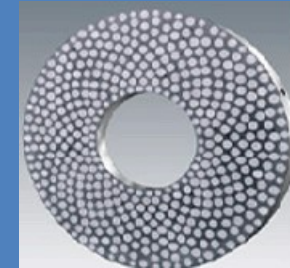
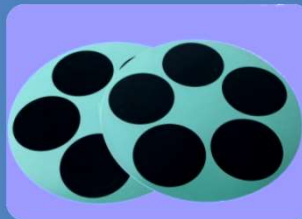
Consumable
耗材

Parts & Tools
配件&工具

Machine Modi &
Repair
设备维修&改造服务

制程服务
Process
Developing

Subcontractors
研磨/抛光代工服务



Lapping Consumable

Polishing Consumable

Fine Grinding Consumable

Products & Service/产品及服务:



Parts & Tools/配件及工具

Machine
设备

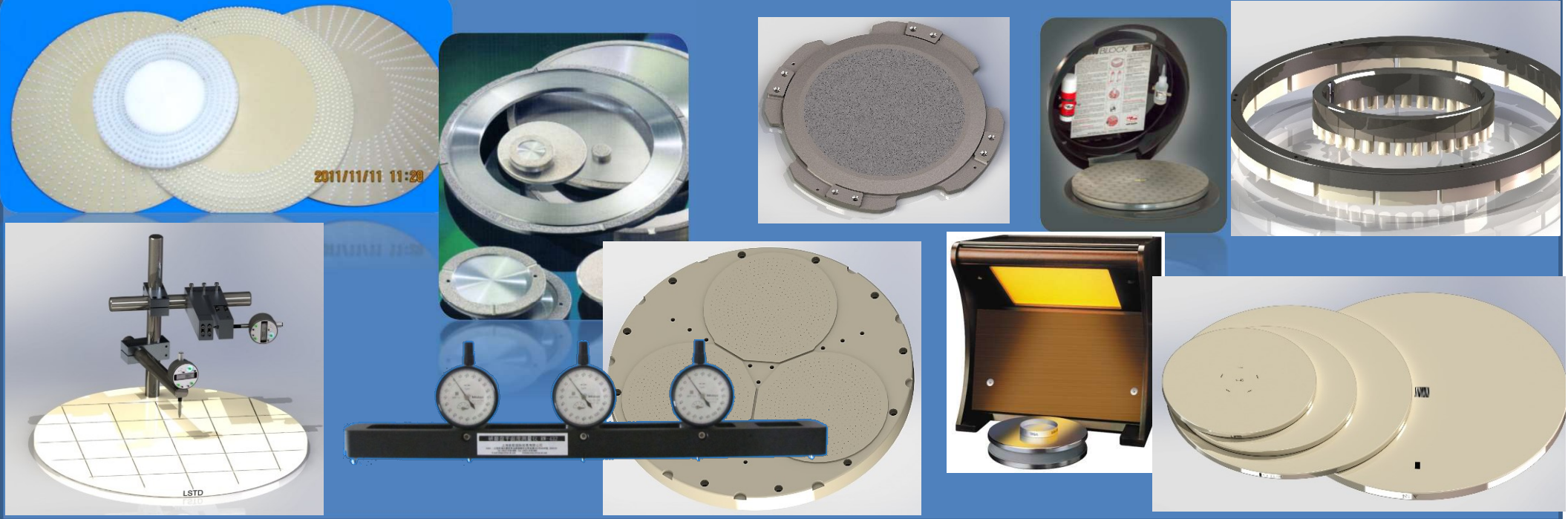
Consumable
耗材

Parts & Tools
配件&工具

Machine Modi &
Repair
设备维修&改造服务

制程服务
Process
Developing

Subcontractors
研磨/抛光代工服务



Products & Service/产品及服务:



Machine modification & Repair/设备维修及改造

Machine
设备

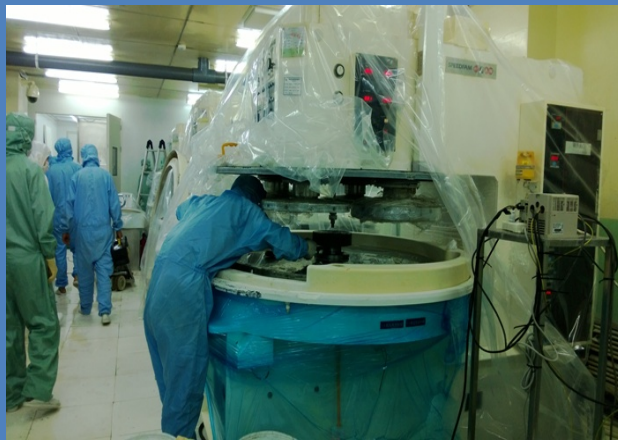
Consumable
耗材

Parts & Tools
配件&工具

Machine Modi &
Repair
设备维修&改造服务

制程服务
Process
Developing

Subcontractors
研磨/抛光代工服务



Function modification & Performance improvement
功能改造&性能提升



Products & Service/产品及服务:

Process R&D/工艺开发

Machine
设备

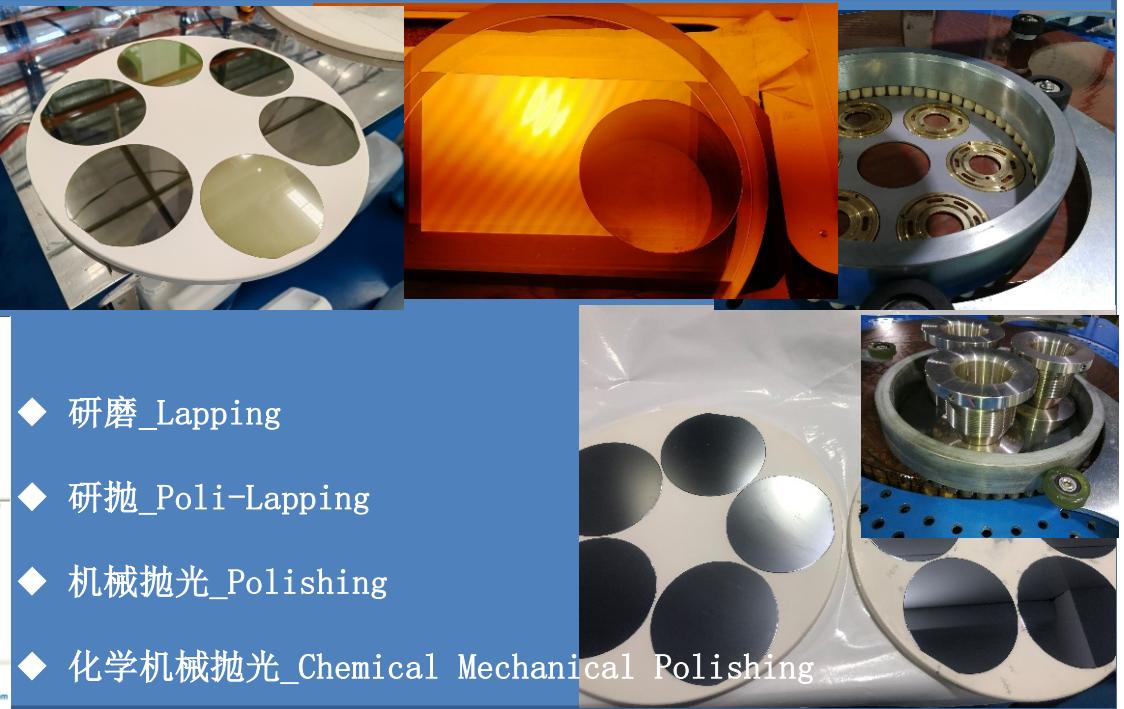
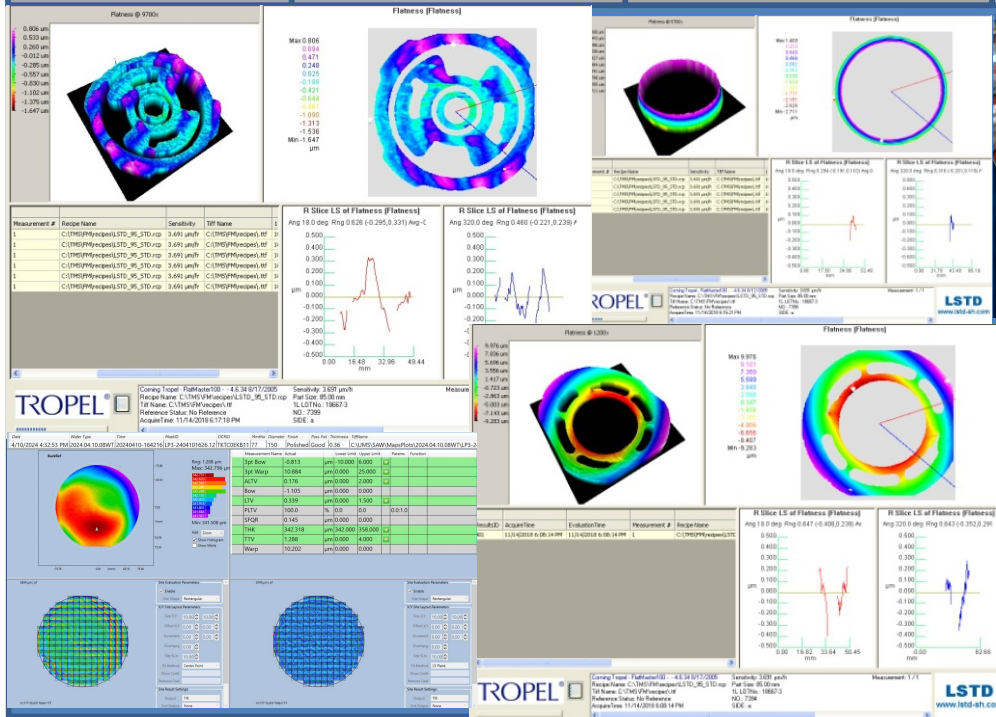
Consumable
耗材

Parts & Tools
配件&工具

Machine Modi &
Repair
设备维修&改造服务

Process
R&D
工艺开发

Subcontractors
研磨/抛光代工服务



- ◆ 研磨_Lapping
- ◆ 研抛_Poli-Lapping
- ◆ 机械抛光_Polishing
- ◆ 化学机械抛光_Chemical Mechanical Polishing

Products & Service/产品及服务:



Subcontractor Service/研磨、抛光代加工服务

(Max Dia: ϕ 1200mm)

Machine
设备

Consumable
耗材

Parts & Tools
配件&工具

Machine Modi &
Repair
设备维修&改造服务

Process
Developing
制程开发服务

Subcontractors
研磨/抛光代工服务





Advantage/优势:

- Focus & Expertise 专注于研磨抛光行业
- Integrated Know-how s in different industries 多行业研磨技术的综合应用及提升
- Wider Covering of Target Market 市场覆盖面广
- Closer to Customers 更贴近客户
- Full range of product line 产品供应更加完整
- Actively Marketing 积极的市场行为
- Matured cooperation model with supplier all over the world 与供应商成熟的配合模式

お問い合わせはOSTECHへ

Contact us to order



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